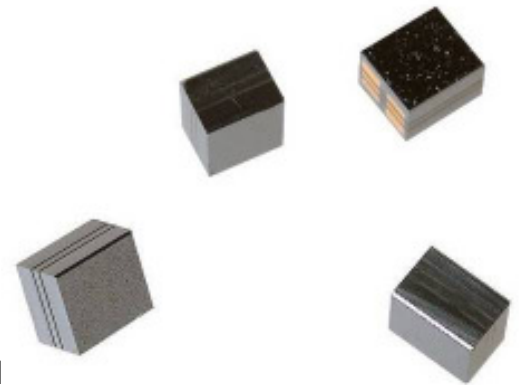


Measuring of Acceleration, Inclination and Vibration:

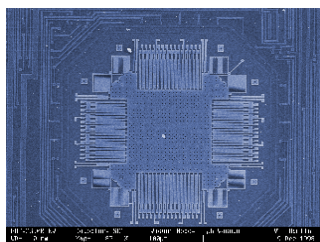
Advantages of improved bulk micro machined MEMS-Technology (=3D-MEMS) of VTI

- Micro g resolution (e.g. $7\mu\text{g}/\sqrt{\text{Hz}}$ noise in SCA103T Series)
- Low Power consumption (used e.g. in pace maker with down to Nano Ampere)
- Excellent long term stability: (e.g. 0,62mg $\approx 0,036^\circ$ stability for 10 years, calculated from HTB tests of SCA61T-serie)
- Excellent temperature stability (e.g. 1..2mg from $-5...70^\circ\text{C}$ for SCA103T Series)
- More than 20'000g shock performance, no parameter drift, hysteresis effects not measurable
- Mechanical vibration and resonance frequencies discrimination

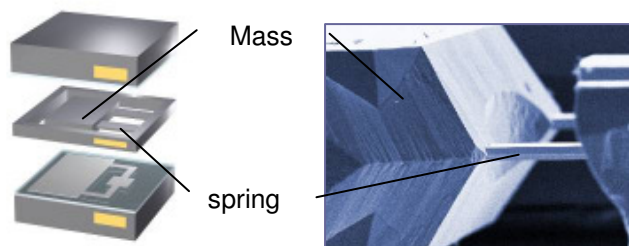


Sensing el
„advnced
micromachined MEMS“

Differences of the two MEMS-Technologies:



Often used “Surface micro machined” (2D MEMS) Technology with very thin structures



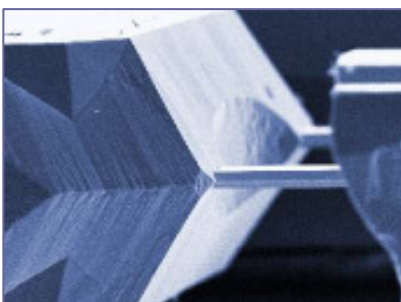
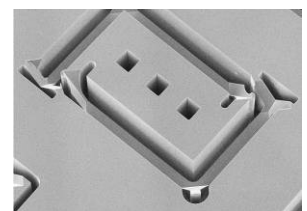
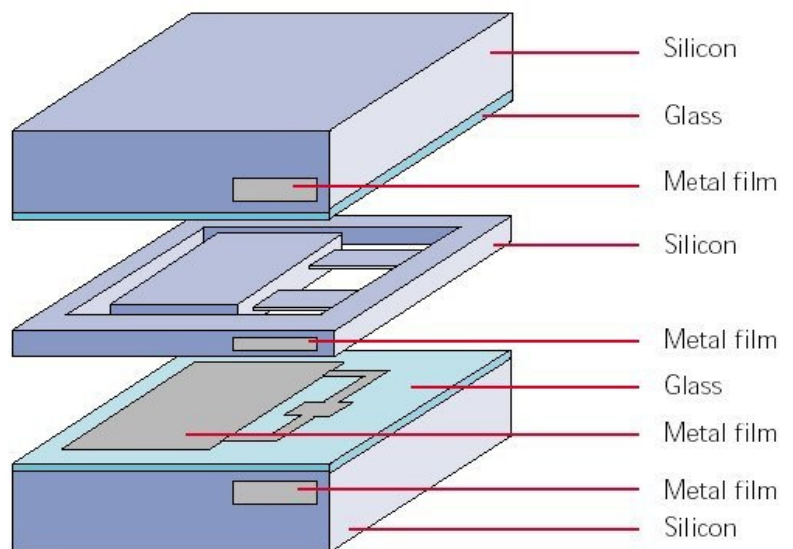
Improved bulk micro machined (3D MEMS)

Why is this possible?

- Real 3D structures: small size high accuracy multi-axis elements (features similar in all three directions)
- Easy contacting for smallest size: smart feed-through structures, solderable / wire bondable element contacts

1-axis 3D-MEMS sensing element

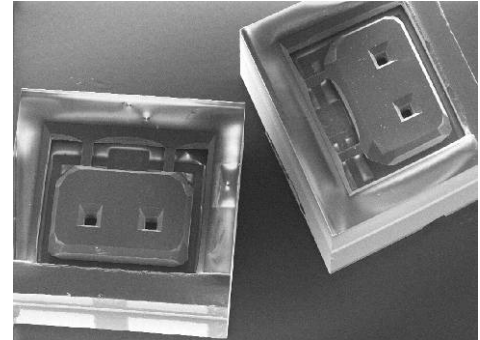
- Flexible 2- and multi-chip solutions
- This improved bulk micro machined technology (3D-MEMS) is a optimized combination of etching (wet and dry), capping (wafer bonding, glass insulation, feed-through structures), contacting (electrodes: solderable, wire bondable)
- Large proof mass in an accelerometer resulting from utilizing the whole or a significant part of the thickness of a silicon wafer – this means high acceleration-to-force conversion ratio, giving large signal and consequently good signal-to-noise and signal-to-unwanted effects ratio



Proof-mass under Electro-microsopce

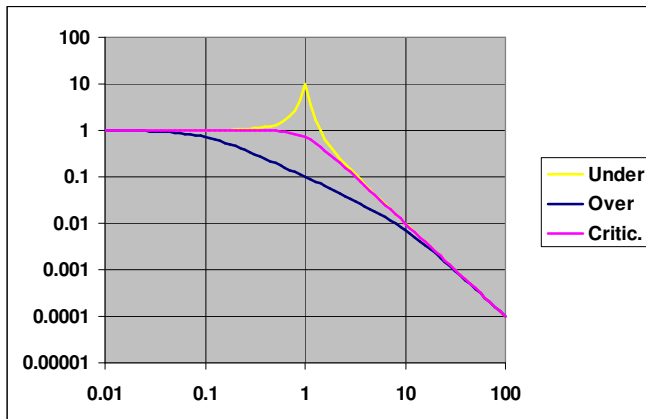
- Large parallel plate capacitance and high capacitance dynamics – same effects as above, makes capacitive measurement and low current consumption easy
- Flexible proof mass, membrane and spring designs – best performance at smallest size

- High shock (~ 50 000g) and over-range capability (no breakage / no stiction) as well as the absence of mechanical hysteresis or plastic deformation resulting from the use of single crystal silicon and advanced designs – this makes the sensors robust at installation/maintenance as well as in use



- High isolation resistance and low stray capacitance – enables ultra low power consumption, easy linear capacitive measurement, increases dynamic range (large signal / good signal to noise ratio)

- High stiffness, high inertia and Q-value in vibrating structures resulting from well defined springs, large proof mass, high amplitude and low internal pressure – ideal technology for vibrating gyros

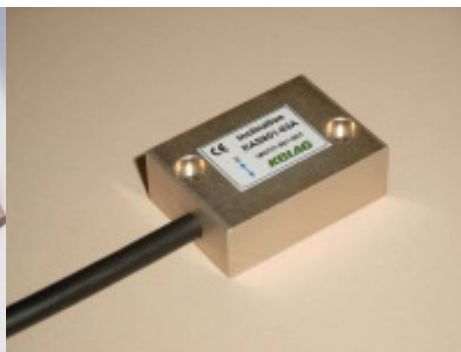


- Optimized frequency behaviour (controlled damping) – enables robust low frequency accelerometers or inclinometers for harsh vibrating environments or wide flat frequency response

Example of our products based on this Bulk-MEMS-Technology:



Rugged IP67/68 Sensor
 4...20mA output
 Modbus (RS485 based)
 Other on request



economic & small Sensor
 0.5....4,5 (-4...+4V) output
 lot of different ranges



customized sensor
 please ask for your application
 our optimal sensor solution.